

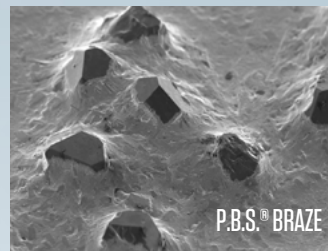
CMP CONDITIONING DISKS

As the pioneer in P.B.S.[®] brazed bonding for CMP pad conditioning disks, Abrasive Technology has set the industry standards for performance, consistency and efficiency.



FEATURES

- Operate on all major CMP equipment platforms in oxide (ILD, STI, POLY, BPSG) and metal (W, Cu) processes.
- Specialized manufacturing technology to control critical abrasive specifications (diamond size, shape, bond height, diamond plane), which delivers high performance.
- Ideal for both in-situ and ex-situ CMP processes to meet critical CMP process requirements.
- Available in magnetic and non-magnetic grades of stainless steel in variety of front surface configurations and sizes.



THE P.B.S.[®] ADVANTAGE

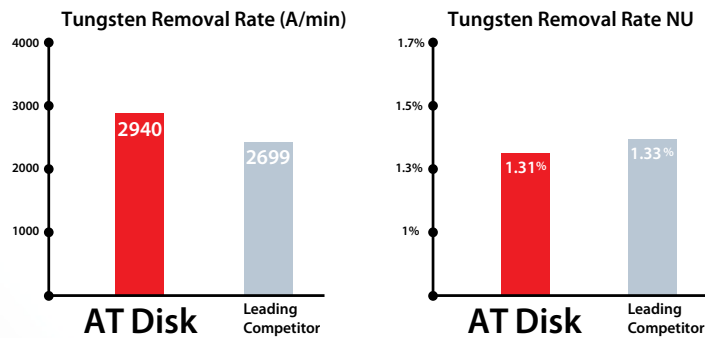
- Individually and permanently brazes diamonds in place, increasing crystal retention.
- Greater control over crystal concentration, creating a more consistent pad surface.
- Chemical bond is more durable than electroplated and protects the crystals, extending the life of each disk.

CMP DISK FOR TUNGSTEN

Abrasive Technology's P.B.S.[®] brazed disks for CMP pad conditioning are precisely manufactured for the highest productivity in semiconductor wafer processing. Our disks are customized to operate on Oxide, Tungsten and Copper processes.



<p>Performance: Third party testing confirmed consistent, high-performance results on AT disks when compared to the leading competitor.</p>	<p>Value: Users achieve lower cost of ownership with AT disk:</p> <ul style="list-style-type: none"> • Improve price • Higher quality • Consistent performance 	<p>Customer Data: Tungsten Process Polishing Tool: <i>EPO112-T/300mm AiGIIS Head</i> Polish Pad: <i>IC1000K/SubaIV</i> Slurry: <i>Cabot</i></p>
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**Diameter Scan (81 pt)
Competitor A vs. AT Disk 1**

